

## Application Specific Discretes A.S.D.™

## **APPLICATIONS**

Where transient overvoltage protection in esd sensitive equipment is required, such as :

- COMPUTERS
- PRINTERS
- COMMUNICATION SYSTEMS

It is particulary recommended for RS232 I/O port protection where the line interface withstands 2 kV, ESD surges.

## **FEATURES**

- 18 BIDIRECTIONAL TRANSIL FUNCTIONS
- LOW CAPACITANCE : C = 30pF @ V<sub>RM</sub>
- 500 W peak pulse power (8/20 μs)

## DESCRIPTION

The ESDA25DB3 is a dual monolithic voltage suppressor designed to protect components which are connected to data and transmission lines against ESD.

#### **BENEFITS**

High ESD protection level : up to 25 kV High integration Suitable for high density boards

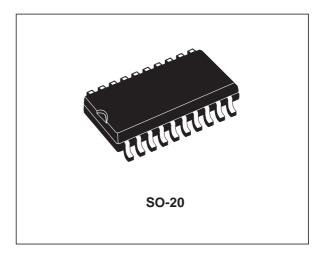
## COMPLIES WITH THE FOLLOWING STANDARDS :

IEC 1000-4-2 : level 4

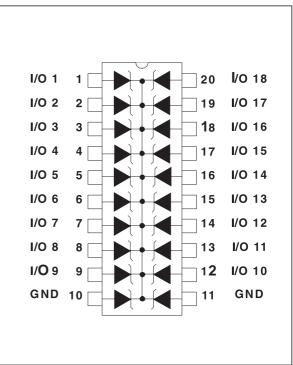
MIL STD 883C-Method 3015-6 : class 3 (human body model)

# ESDA25DB3

## TRANSIL ARRAY FOR ESD PROTECTION



## FUNCTIONAL DIAGRAM



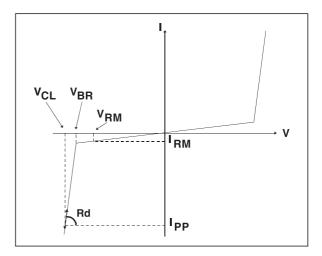
## ESDA25DB3

## ABSOLUTE MAXIMUM RATINGS (Tamb = 25°C)

Symbol	Parameter	Value	Unit
V <sub>PP</sub>	Electrostatic discharge MIL STD 883C - Method 3015-6	25	kV
P <sub>PP</sub>	Peak pulse power (8/20μs)	500	W
T <sub>stg</sub> T <sub>j</sub>	Storage temperature range Maximum junction temperature	- 55 to + 150 125	°C ℃
TL	Maximum lead temperature for soldering during 10s	260	°C

## ELECTRICAL CHARACTERISTICS (Tamb = 25°C)

Symbol	Parameter					
V <sub>RM</sub>	Stand-off voltage					
V <sub>BR</sub>	Breakdown voltage					
V <sub>CL</sub>	Clamping voltage					
I <sub>RM</sub>	Leakage current					
IPP	Peak pulse current					
ατ	Voltage temperature coefficient					
С	Capacitance					



57

Types	V <sub>BR</sub> @		I <sub>R</sub>	I <sub>RM</sub> @	Vrm	Rd	αΤ	с
	min.	max.		max.		typ.	max.	typ.
	note1			note1		note 2	note 3	0V bias
	V	V	mA	μA	V	Ω	10 <sup>-4</sup> /°C	pF
ESDA25DB3	25	30	1	2	24	0.5	9.7	50

 $\begin{array}{l} \textbf{note 1}: \text{Betwenn any I/O pin Groung} \\ \textbf{note 2}: \text{Square pulse, Ipp} = 25\text{A}, \text{tp} = 2.5 \mu\text{s}. \\ \textbf{note 3}: \ \Delta \ \text{V}_{BR} = \alpha \text{T}^* \ (\text{Tamb -}25^\circ\text{C})^* \ \text{V}_{BR} \ (25^\circ\text{C}) \end{array}$ 

## CALCULATION OF THE CLAMPING VOLTAGE

## USE OF THE DYNAMIC RESISTANCE

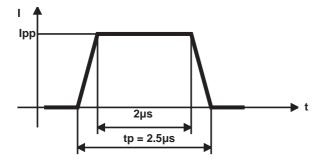
The ESDA family has been designed to clamp fast spikes like ESD. Generally the PCB designers need to calculate easily the clamping voltage  $V_{CL}$ . This is why we give the dynamic resistance in addition to the classical parameters. The voltage across the protection cell can be calculated with the following formula:

 $V_{CL} = V_{BR} + Rd I_{PP}$ 

Where lpp is the peak current through the ESDA cell.

## DYNAMIC RESISTANCE MEASUREMENT

The short duration of the ESD has led us to prefer a more adapted test wave, as below defined, to the classical  $8/20\mu s$  and  $10/1000\mu s$  surges.



2.5µs duration measurement wave.

As the value of the dynamic resistance remains stable for a surge duration lower than  $20\mu$ s, the 2.5 $\mu$ s rectangular surge is well adapted. In addition both rise and fall times are optimized to avoid any parasitic phenomenon during the measurement of Rd.

57

## ESDA25DB3

**Fig. 1 :** Peak power dissipation versus initial junction tempearature.

Ppp[Tj initial]/Ppp[Tj initial=25°C] 1.1 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 Tj initial(°C) 0.1 0.0 L 0.0 0 25 75 100 50 125 150 **Fig. 2**: Peak pulse power versus exponential pulse duration (Tj initial = 25 °C).

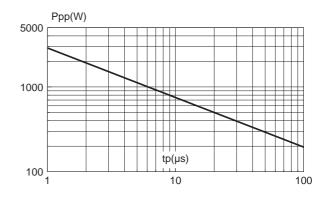
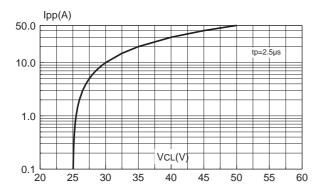
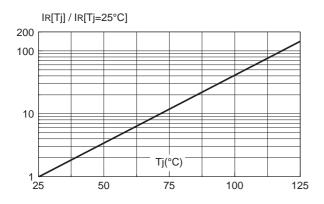


Fig. 3 : Clamping voltage versus peak pulse current (Tj initial = 25 °C).

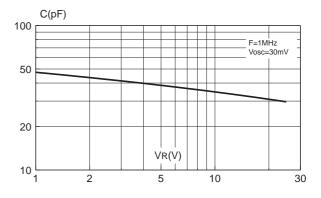
Rectangular waveform tp =  $2.5 \,\mu s$ .



**Fig. 5** : Relative variation of leakage current versus junction temperature (typical values).

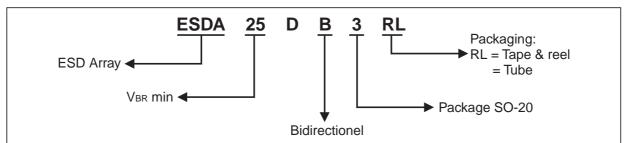


**Fig. 4** : Capacitance versus reverse applied voltage (typical values).



57

#### **ORDER CODE**



## PACKAGE MECHANICAL DATA

SO-20 Plastic

		DIMENSIONS						
	REF.	Millimetres			Inches			
D → + + + + + + + + + + + + + + + + + +		Min.	Тур.	Max.	Min.	Тур.	Max.	
	Α			2.65			0.104	
	A1	0.10		0.20	0.004		0.008	
	В	0.33		0.51	0.013		0.020	
	С	0.23		0.32	0.009		0.013	
	D	12.6		13.0	0.484		0.512	
Ен	E	7.40		7.60	0.291		0.299	
	е		1.27			0.050		
	Н	10.0		10.65	0.394		0.419	
	h		0.50			0.020		
	L	0.50		1.27	0.020		0.050	
	К	8° (max)						

Marking: Logo, Date Code, E25DB3 Packaging: Preferred packaging is tape and reel. Weight: 0.55g.

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics

© 2001 STMicroelectronics - Printed in Italy - All rights reserved.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com

57